PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16335
1.3 Title of PCN	ST Shenzhen (China) matte Tin post plating introduction for 1Kb to 128Kb I^{2}C EEPROM in SO8N
1.4 Product Category	Low densities EEPROM I^{2}C in SO8N from 1Kb to 128Kb.
1.5 Issue date	2026-05-13

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	David RICHETTO
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame finishing material / area (internal)	N/A

4. Description of change

	Old	**New**
4.1 Description	The low densities EEPROM I^{2}C from 1Kb to 128Kb, processed with the CMOS F8H+ technology, currently assembled in SO8N at ST Shenzhen (China) with NiPdAgAu pre-plated frame...	...will be now assembled with matte Tin post-plated frame.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: Matte appearance of leads compared to NiPdAgAu pre-plated leadframe - Fit: No change - Function: No change	

5. Reason / motivation for change

5.1 Motivation	The strategy of the STMicroelectronics Memory division is to support our customers on products and service quality on a long-term basis. In line with this commitment, the qualification of the matte Tin post-plating at ST Shenzhen will allow us to increase capacity and reinforce long term competitiveness. For optimal service and security of double sourcing, this PCN is coupled with the TSHT PCN (16143 & 16334).
5.2 Customer Benefit	DOUBLE SOURCING

6. Marking of parts / traceability of change

6.1 Description	N/A

7. Timing / schedule

7.1 Date of qualification results	2026-07-06
7.2 Intended start of delivery	2026-08-10
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16335 RRCS2522 Reliability report F8H SO8N SHZ Postplating.pdf

8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-05-13

9. Attachments (additional documentations)
16335 Public product.pdf 16335 PCN TIN PLATING SO8 SHENZHEN.pdf 16335 RRCS2522 Reliability report F8H SO8N SHZ Postplating.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	M24128-BRMN6TP	
	M24C01-RMN6TP	
	M24C02-RMN6TP	
	M24C02-WMN6TP	
	M24C32-WMN6TP	

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